

**3GPP TSG RAN#8**  
**Dusseldorf, Germany, 21 -23 June, 2000**

***RP (00)0312***

**Agenda Item: 6**

**Source: CWTS**

**To: RAN#8**

**Title: Proposed WI " Low chip rate TDD layer 2 and layer 3  
protocol aspects"**

**Document for: Approval**

## Work Item Description

### Title

Low chip rate TDD layer 2 and layer 3 protocol aspects

### 1 3GPP Work Area

<b>X</b>	Radio Access
	Core Network
	Services

### 2 Linked work items

*Low Chip Rate TDD physical layer*  
*Low chip rate TDD UTRAN architecture aspects*  
*Smart Antenna*  
*RF Radio Transmission/Reception, System Performance Requirements and Conformance Testing*  
*Low chip rate TDD UE radio access capabilities*

### 3 Justification

The integration of TDD low chip rate option in Release 2000 was discussed and approved in RAN#6. The work plan of the integration of low chip rate TDD in R00 was discussed in RAN#7. As a feature, the low chip rate TDD is sub-divided into several building blocks via the email discussion. Although most of the L2/L3 features are common with high chip rate TDD option , there are some differences ,e.g. modification of signalling, baton handover etc., which should be described and clarified. Basically, most of them were originated from the differences of physical layer between low chip rate TDD and UTRA TDD and the involvement of Smart Antenna. This paper is to describe one of the low chip rate TDD building blocks – layer 2 and layer 3 protocol aspects.

### 4 Objective

The technical objective of this work item is to complete the low chip rate TDD L2/L3 functionality adaptation in UTRA TDD. And this work will affect the specifications for working group on L2/L3.

- For layer 2 and layer 3 protocol aspects, it includes the following work tasks:
  - UE procedures in idle mode
  - Interlayer procedures in connected mode
  - Control plane protocol aspects
  - User plane protocol aspects
  - Baton Handover and mobility aspects

Task	Planned Start	Planned Finish
Prepare technical inputs	04/2000	06/2000
Drafting, change request and possible new specs	06/2000	09/2000
Possible corrections	09/2000	12/2000

### 5 Service Aspects

None

**6 MMI-Aspects**

None

**7 Charging Aspects**

None

**8 Security Aspects**

None

**9 Impacts**

<b>Affects :</b>	<b>USIM</b>	<b>ME</b>	<b>AN</b>	<b>CN</b>	<b>Others</b>
<b>Yes</b>		X	X		
<b>No</b>	X			X	X
<b>Don't know</b>					

**10 Expected Output and Time scale (to be updated at each plenary)**

<b>New specifications</b>						
Spec No.	Title	Prime rsp. WG	2ndary rsp. WG(s)	Presented for information at plenary#	Approved at plenary#	Comments
<b>Affected existing specifications</b>						
Spec No.	CR	Subject			Approved at plenary#	Comments
25.301		Radio interface protocol architecture			RAN#9	
25.302		Service provided by the physical Layer			RAN#9	
25.303		UE functions and Inter-layer procedures in connected mode			RAN#9	
25.304		UE procedures in idle mode and procedures for cell reselection in connected mode			RAN#9	
25.305		Stage 2 functional specification of location service in UTRAN (LCS)			RAN#9	
25.321		Medium access control (MAC) protocol specification			RAN#9	
25.322		Radio link control(RLC) protocol specification			RAN#9	
25.331		Radio resource control (RRC) protocol specification			RAN#9	
25.324		Radio Interface for Broadcast/Multicast Services			RAN#9	
25.925		Radio Interface for Broadcast/Multicast Services			RAN#9	
25.922		Radio Resource Management Strategies			RAN#9	

**11 Work item raporteurs**

Mr. Yanhui LIU (CATT/CWTS)

**12 Work item leadership**

RAN WG2

**13 Supporting Companies**

Ericsson, Fujitsu, IDC, LG, NTT DoCoMo, Panasonic, RFI, Samsung, Siemens

**14 Classification of the WI (if known)**

	Feature (go to 14a)
X	Building Block (go to 14b)
	Work Task (go to 14c)

14a The WI is a Feature: List of building blocks under this feature

(list of Work Items identified as building blocks)

14b The WI is a Building Block: parent Feature

low chip rate TDD

14c The WI is a Work Task: parent Building Block

(one Work Item identified as a building block)